

The RF Sub-Micron MOSFET Line

RF Power Field Effect Transistors

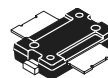
N-Channel Enhancement-Mode Lateral MOSFETs

Designed for broadband commercial and industrial applications with frequencies up to 1.0 GHz. The high gain and broadband performance of these devices make them ideal for large-signal, common-source amplifier applications in 28 volt base station equipment.

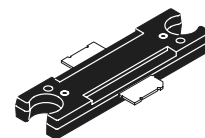
- Typical Performance at 945 MHz, 28 Volts
Output Power — 45 Watts PEP
Power Gain — 19 dB
Efficiency — 41% (Two Tones)
IMD — -31 dBc
- Integrated ESD Protection
- Guaranteed Ruggedness @ Load VSWR = 5:1, @ 28 Vdc, 945 MHz, 45 Watts CW Output Power
- Excellent Thermal Stability
- Characterized with Series Equivalent Large-Signal Impedance Parameters
- Moisture Sensitivity Level 3
- Dual-Lead Boltdown Plastic Package Can Also Be Used As Surface Mount.
- TO-272 Available in Tape and Reel. R1 Suffix = 500 Units per 44 mm, 13 inch Reel.
- TO-270 Available in Tape and Reel. R1 Suffix = 500 Units per 24 mm, 13 inch Reel.

MRF9045MR1
MRF9045MBR1

945 MHz, 45 W, 28 V
LATERAL N-CHANNEL
BROADBAND
RF POWER MOSFETs



CASE 1265-07, STYLE 1
TO-270
PLASTIC
MRF9045MR1



CASE 1337-02, STYLE 1
TO-272 DUAL LEAD
PLASTIC
MRF9045MBR1

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	65	Vdc
Gate-Source Voltage	V_{GS}	+15, -0.5	Vdc
Total Device Dissipation @ $T_C = 25^\circ\text{C}$ Derate above 25°C	P_D	177 1.18	Watts W/ $^\circ\text{C}$
Storage Temperature Range	T_{stg}	-65 to +150	$^\circ\text{C}$
Operating Junction Temperature	T_J	175	$^\circ\text{C}$

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction to Case	$R_{\theta JC}$	0.85	$^\circ\text{C/W}$

ESD PROTECTION CHARACTERISTICS

Test Conditions	Class
Human Body Model	1 (Minimum)
Machine Model	M2 (Minimum)

NOTE – **CAUTION** – MOS devices are susceptible to damage from electrostatic charge. Reasonable precautions in handling and packaging MOS devices should be observed.

ELECTRICAL CHARACTERISTICS ($T_C = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
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OFF CHARACTERISTICS

Zero Gate Voltage Drain Leakage Current ($V_{DS} = 65\text{ Vdc}$, $V_{GS} = 0\text{ Vdc}$)	I_{DSS}	—	—	10	μAdc
Zero Gate Voltage Drain Leakage Current ($V_{DS} = 28\text{ Vdc}$, $V_{GS} = 0\text{ Vdc}$)	I_{DSS}	—	—	1	μAdc
Gate–Source Leakage Current ($V_{GS} = 5\text{ Vdc}$, $V_{DS} = 0\text{ Vdc}$)	I_{GSS}	—	—	1	μAdc

ON CHARACTERISTICS

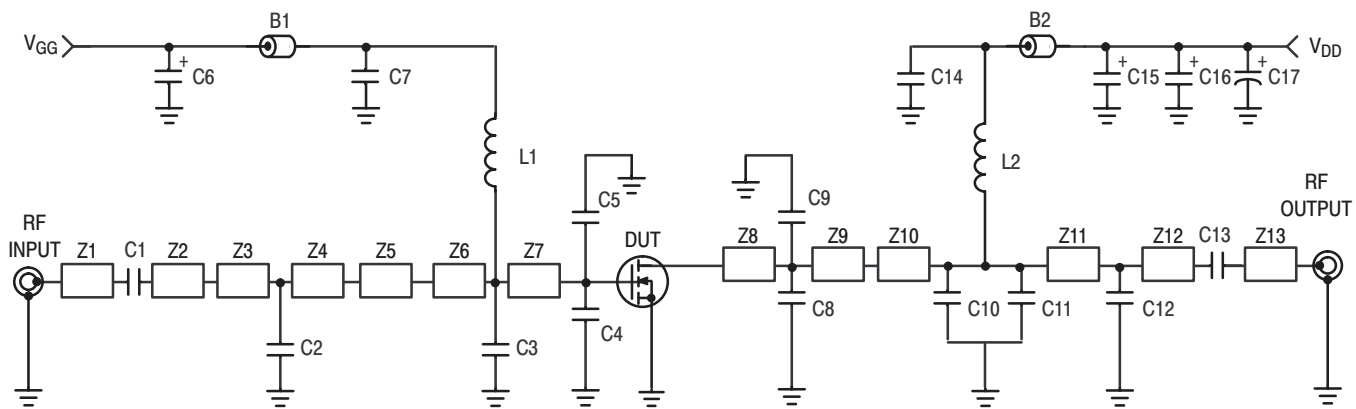
Gate Threshold Voltage ($V_{DS} = 10\text{ Vdc}$, $I_D = 150\text{ }\mu\text{Adc}$)	$V_{GS(th)}$	2	2.8	4	Vdc
Gate Quiescent Voltage ($V_{DS} = 28\text{ Vdc}$, $I_D = 350\text{ mAdc}$)	$V_{GS(Q)}$	3	3.7	5	Vdc
Drain–Source On–Voltage ($V_{GS} = 10\text{ Vdc}$, $I_D = 1\text{ Adc}$)	$V_{DS(on)}$	—	0.22	0.4	Vdc
Forward Transconductance ($V_{DS} = 10\text{ Vdc}$, $I_D = 3\text{ Adc}$)	g_{fs}	—	4	—	S

DYNAMIC CHARACTERISTICS

Input Capacitance ($V_{DS} = 28\text{ Vdc} \pm 30\text{ mV(rms)ac}$ @ 1 MHz, $V_{GS} = 0\text{ Vdc}$)	C_{iss}	—	70	—	pF
Output Capacitance ($V_{DS} = 28\text{ Vdc} \pm 30\text{ mV(rms)ac}$ @ 1 MHz, $V_{GS} = 0\text{ Vdc}$)	C_{oss}	—	38	—	pF
Reverse Transfer Capacitance ($V_{DS} = 28\text{ Vdc} \pm 30\text{ mV(rms)ac}$ @ 1 MHz, $V_{GS} = 0\text{ Vdc}$)	C_{rss}	—	1.7	—	pF

FUNCTIONAL TESTS (In Motorola Test Fixture, 50 ohm system)

Two–Tone Common–Source Amplifier Power Gain ($V_{DD} = 28\text{ Vdc}$, $P_{out} = 45\text{ W PEP}$, $I_{DQ} = 350\text{ mA}$, $f_1 = 945.0\text{ MHz}$, $f_2 = 945.1\text{ MHz}$)	G_{ps}	17	19	—	dB
Two–Tone Drain Efficiency ($V_{DD} = 28\text{ Vdc}$, $P_{out} = 45\text{ W PEP}$, $I_{DQ} = 350\text{ mA}$, $f_1 = 945.0\text{ MHz}$, $f_2 = 945.1\text{ MHz}$)	η	38	41	—	%
3rd Order Intermodulation Distortion ($V_{DD} = 28\text{ Vdc}$, $P_{out} = 45\text{ W PEP}$, $I_{DQ} = 350\text{ mA}$, $f_1 = 945.0\text{ MHz}$, $f_2 = 945.1\text{ MHz}$)	IMD	—	–31	–28	dBc
Input Return Loss ($V_{DD} = 28\text{ Vdc}$, $P_{out} = 45\text{ W PEP}$, $I_{DQ} = 350\text{ mA}$, $f_1 = 945.0\text{ MHz}$, $f_2 = 945.1\text{ MHz}$)	IRL	—	–14	–9	dB
Two–Tone Common–Source Amplifier Power Gain ($V_{DD} = 28\text{ Vdc}$, $P_{out} = 45\text{ W PEP}$, $I_{DQ} = 350\text{ mA}$, $f_1 = 930.0\text{ MHz}$, $f_2 = 930.1\text{ MHz}$ and $f_1 = 960.0\text{ MHz}$, $f_2 = 960.1\text{ MHz}$)	G_{ps}	—	19	—	dB
Two–Tone Drain Efficiency ($V_{DD} = 28\text{ Vdc}$, $P_{out} = 45\text{ W PEP}$, $I_{DQ} = 350\text{ mA}$, $f_1 = 930.0\text{ MHz}$, $f_2 = 930.1\text{ MHz}$ and $f_1 = 960.0\text{ MHz}$, $f_2 = 960.1\text{ MHz}$)	η	—	41	—	%
3rd Order Intermodulation Distortion ($V_{DD} = 28\text{ Vdc}$, $P_{out} = 45\text{ W PEP}$, $I_{DQ} = 350\text{ mA}$, $f_1 = 930.0\text{ MHz}$, $f_2 = 930.1\text{ MHz}$ and $f_1 = 960.0\text{ MHz}$, $f_2 = 960.1\text{ MHz}$)	IMD	—	–31	—	dBc
Input Return Loss ($V_{DD} = 28\text{ Vdc}$, $P_{out} = 45\text{ W PEP}$, $I_{DQ} = 350\text{ mA}$, $f_1 = 930.0\text{ MHz}$, $f_2 = 930.1\text{ MHz}$ and $f_1 = 960.0\text{ MHz}$, $f_2 = 960.1\text{ MHz}$)	IRL	—	–13	—	dB



B1, B2	Short Ferrite Beads, Surface Mount	Z3	0.14" x 0.32" Microstrip
C1, C7, C13, C14	47 pF Chip Capacitors, B Case	Z4	0.47" x 0.32" Microstrip
C2, C8	2.7 pF Chip Capacitors, B Case	Z5	0.16" x 0.32" x 0.62" Taper
C3	3.9 pF Chip Capacitor, B Case	Z6	0.18" x 0.62" Microstrip
C4, C5, C8, C9	10 pF Chip Capacitors, B Case	Z7	0.56" x 0.62" Microstrip
C6, C15, C16	10 μ F, 35 V Tantalum Surface Mount Capacitors	Z8	0.33" x 0.32" Microstrip
C10	2.2 pF Chip Capacitor, B Case	Z9	0.14" x 0.32" Microstrip
C11	4.7 pF Chip Capacitor, B Case	Z10	0.36" x 0.08" Microstrip
C12	1.2 pF Chip Capacitor, B Case	Z11	1.01" x 0.08" Microstrip
C17	220 μ F, 50 V Electrolytic Capacitor	Z12	0.15" x 0.08" Microstrip
L1, L2	12.5 nH Inductors	Z13	0.29" x 0.08" Microstrip
Z1	0.20" x 0.08" Microstrip		
Z2	0.57" x 0.12" Microstrip		

Figure 1. MRF9045MR1 930-960 MHz Broadband Test Circuit Schematic

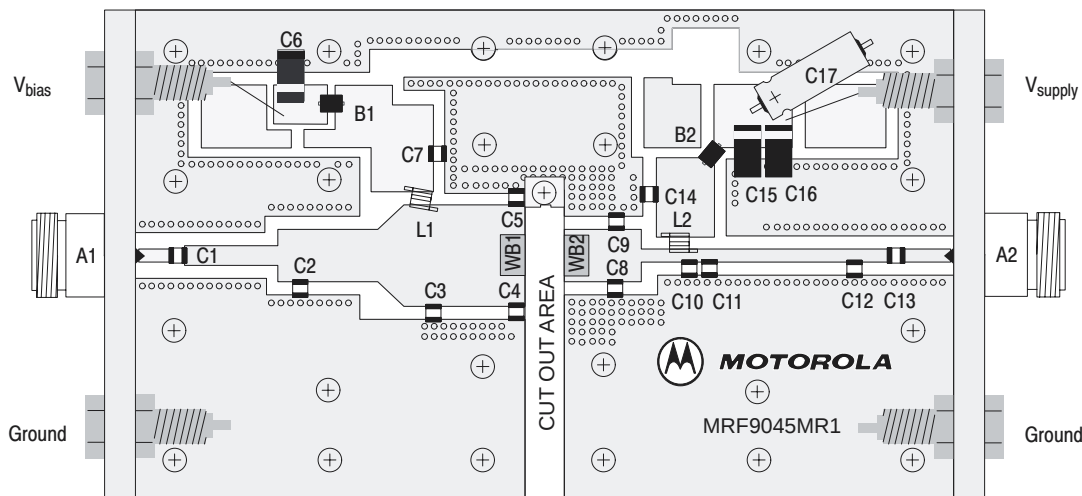
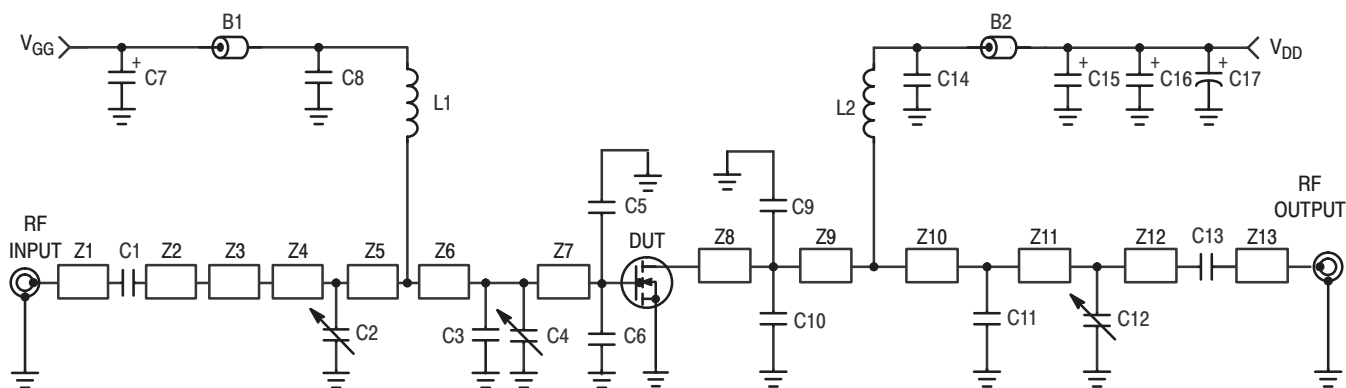


Figure 2. MRF9045MR1 930-960 MHz Broadband Test Circuit Component Layout



B1	Short Ferrite Bead	Z1	0.260" x 0.060" Microstrip
B2	Long Ferrite Bead	Z2	0.240" x 0.060" Microstrip
C1, C8, C13, C14	47 pF Chip Capacitors, B Case	Z3	0.500" x 0.100" Microstrip
C2	0.4–2.5 pF Variable Capacitor, Johanson Gigatrim	Z4	0.215" x 0.270" Microstrip
C3	3.6 pF Chip Capacitor, B Case	Z5	0.315" x 0.270" Microstrip
C4	0.8–8.0 pF Variable Capacitor, Johanson Gigatrim	Z6	0.160" x 0.270" x 0.520" Taper
C5, C6, C9, C10	10 pF Chip Capacitors, B Case	Z7	0.285" x 0.520" Microstrip
C7, C15, C16	10 μ F, 35 V Tantalum Chip Capacitors	Z8	0.140" x 0.270" Microstrip
C11	7.5 pF Chip Capacitor, B Case	Z9	0.450" x 0.270" Microstrip
C12	0.6–4.5 pF Variable Capacitor, Johanson Gigatrim	Z10	0.250" x 0.060" Microstrip
C17	220 μ F Electrolytic Chip Capacitor	Z11	0.720" x 0.060" Microstrip
L1, L2	12.5 nH Surface Mount Inductors	Z12	0.490" x 0.060" Microstrip
WB1, WB2	10 mil Brass Wear Blocks	Z13	0.290" x 0.060" Microstrip
		Board	Taconic RF–35–0300, $\epsilon_r = 3.5$

Figure 3. MRF9045MBR1 930–960 MHz Broadband Test Circuit Schematic

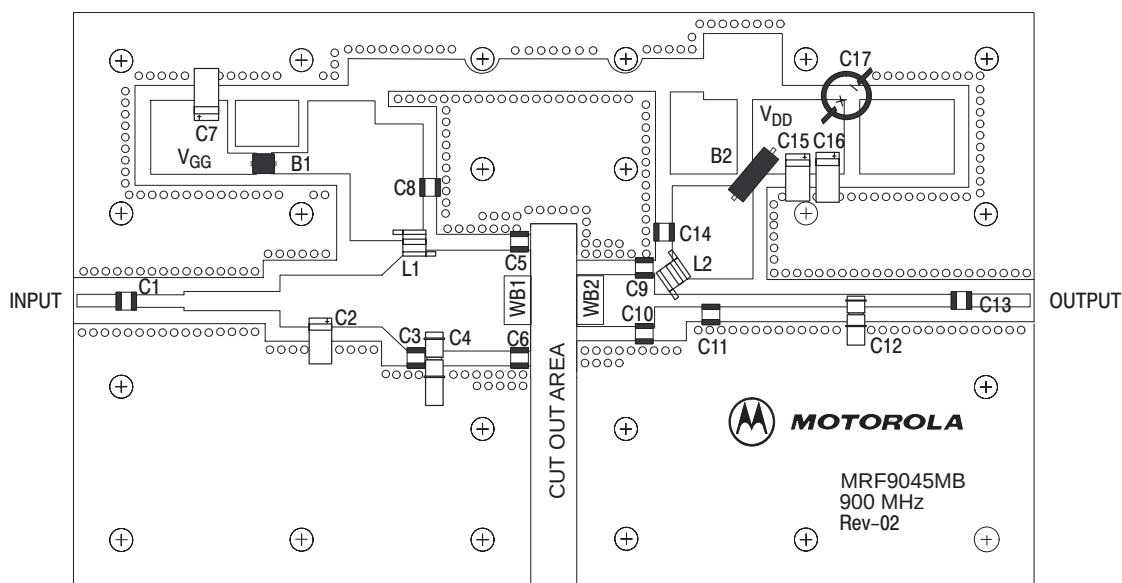


Figure 4. MRF9045MBR1 930–960 MHz Broadband Test Circuit Component Layout

TYPICAL CHARACTERISTICS

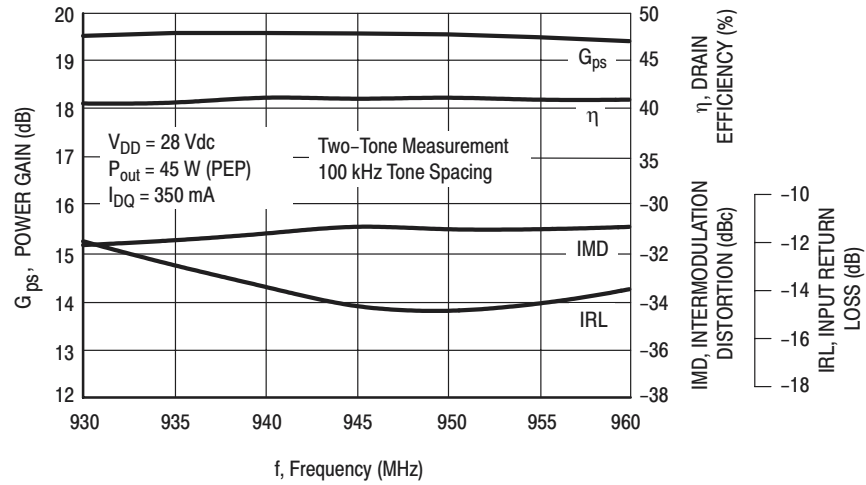


Figure 5. Class AB Broadband Circuit Performance

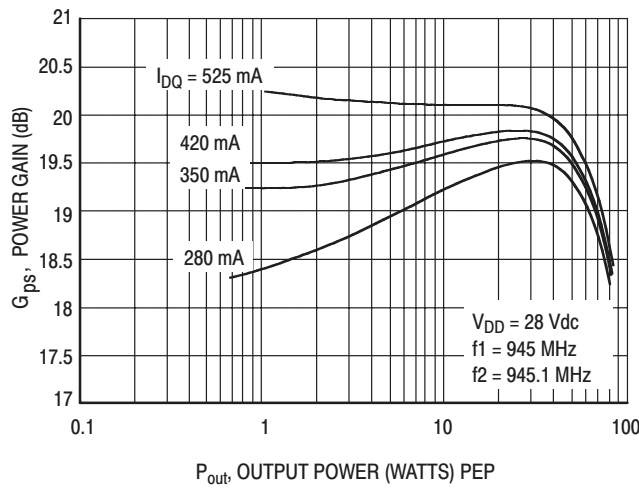


Figure 6. Power Gain versus Output Power

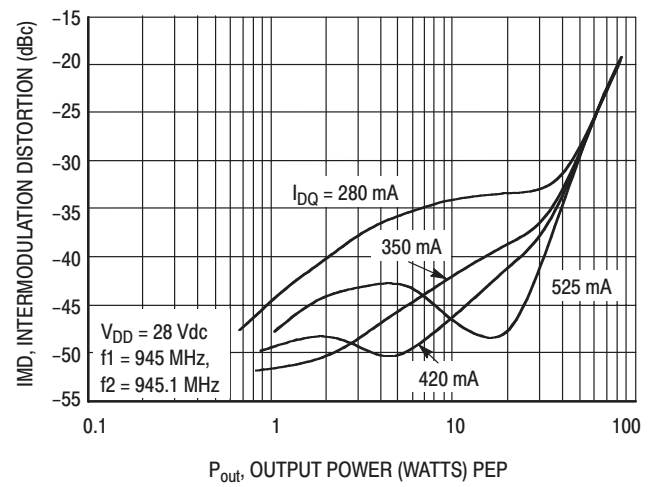


Figure 7. Intermodulation Distortion versus Output Power

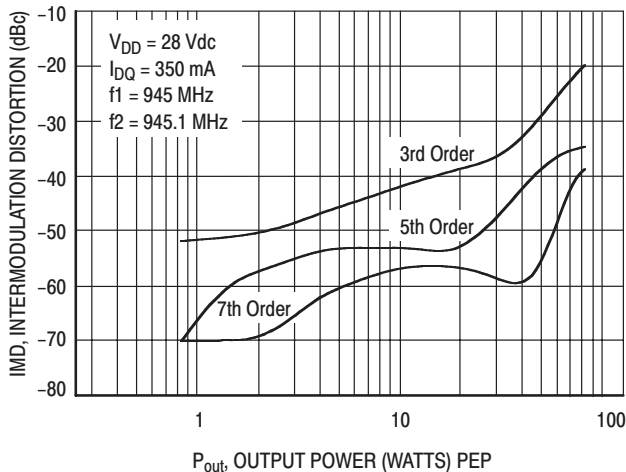


Figure 8. Intermodulation Distortion Products versus Output Power

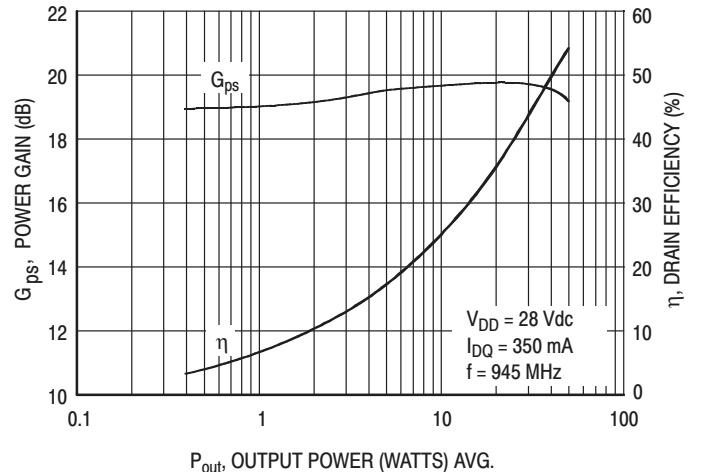


Figure 9. Power Gain and Efficiency versus Output Power

TYPICAL CHARACTERISTICS

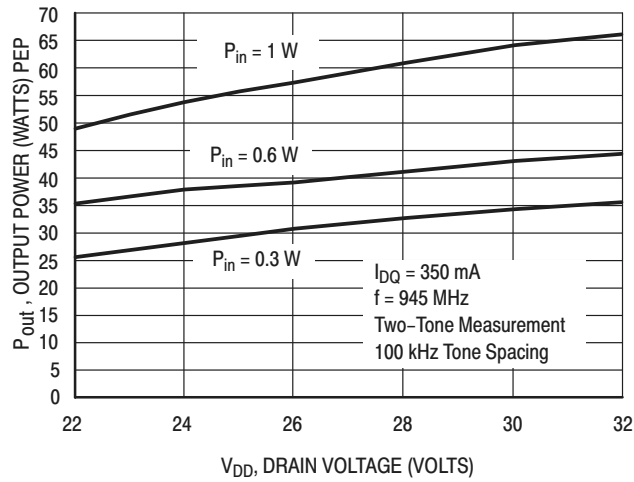


Figure 10. Output Voltage versus Supply Voltage (MRF9045MR1)

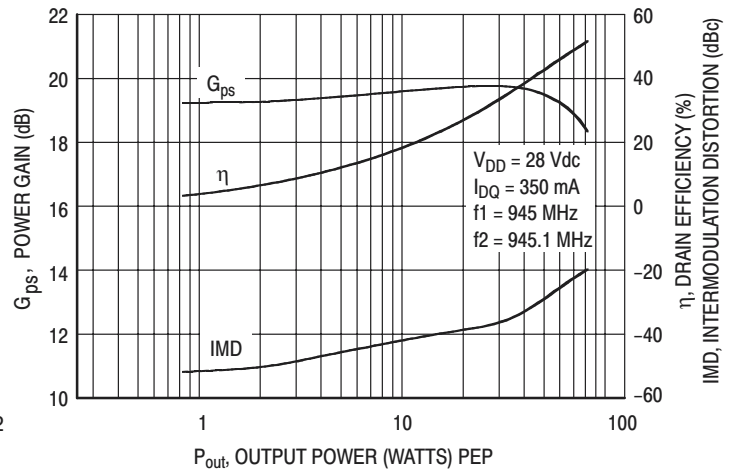
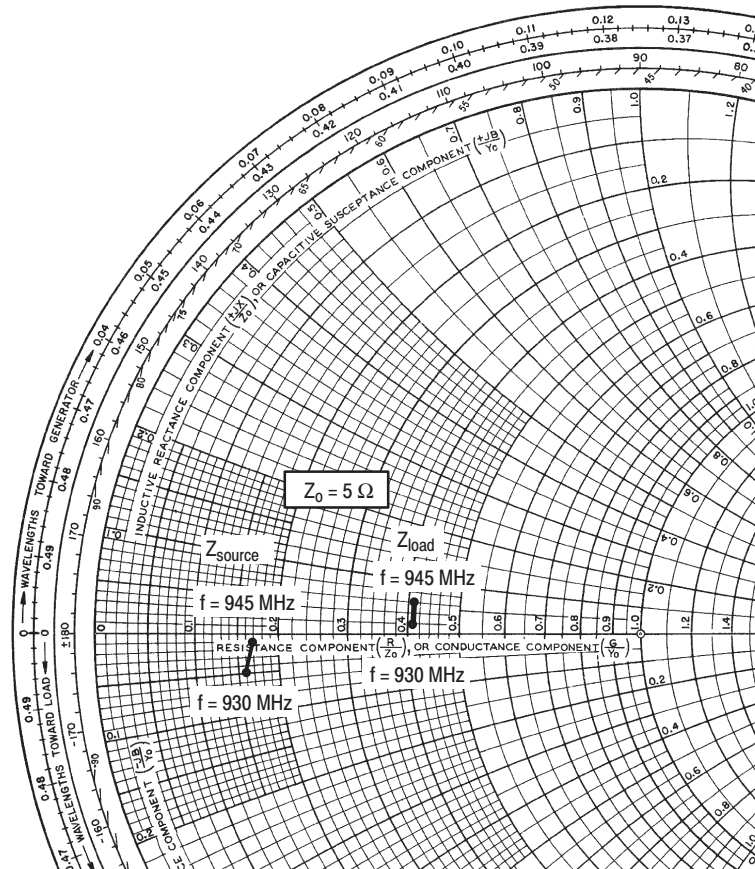


Figure 11. Power Gain, Efficiency and IMD versus Output Power (MRF9045MR1)



$V_{DD} = 28 \text{ V}$, $I_{DQ} = 350 \text{ mA}$, $P_{out} = 45 \text{ W (PEP)}$

f MHz	Z_{source} Ω	Z_{load} Ω
930	$0.81 - j0.25$	$2.03 + j0.09$
945	$0.85 - j0.05$	$2.03 + j0.28$

Z_{source} = Test circuit impedance as measured from gate to ground.

Z_{load} = Test circuit impedance as measured from drain to ground.

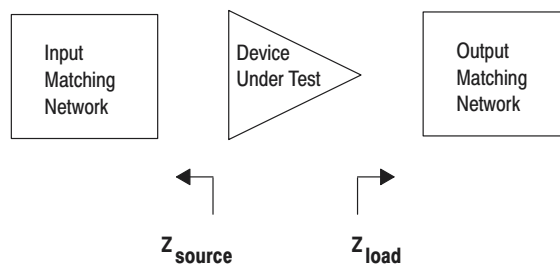
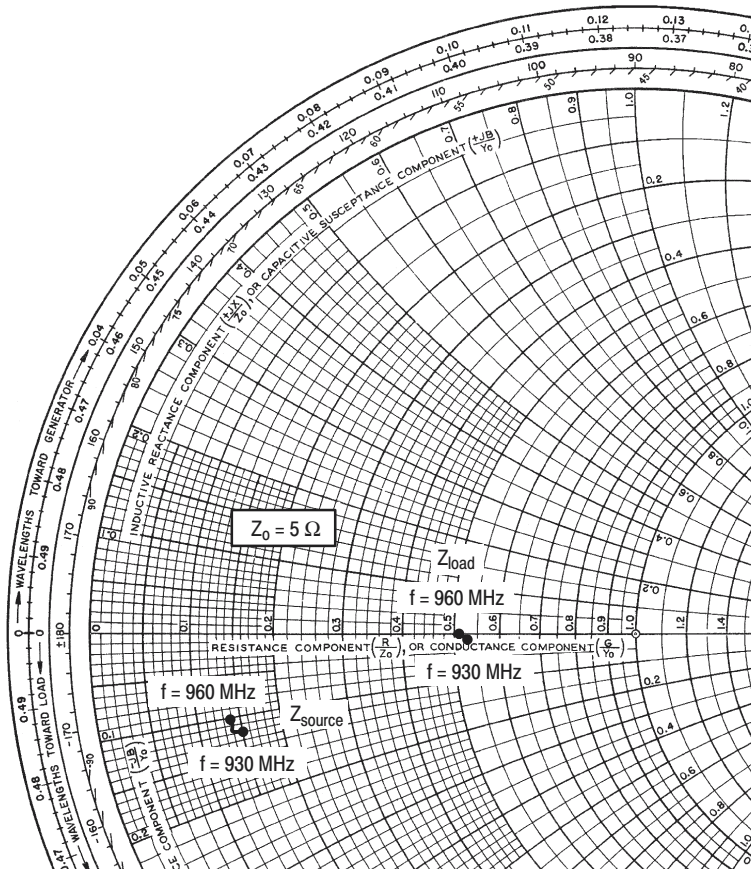


Figure 12. Series Equivalent Input and Output Impedance (MRF9045MR1)



$V_{DD} = 28 \text{ V}$, $I_{DQ} = 350 \text{ mA}$, $P_{out} = 45 \text{ W (PEP)}$

f MHz	Z_{source} Ω	Z_{load} Ω
930	$0.75 - j0.6$	$2.65 - j0.05$
945	$0.72 - j0.6$	$2.60 - j0.05$
960	$0.70 - j0.5$	$2.55 - j0.02$

Z_{source} = Test circuit impedance as measured from gate to ground.

Z_{load} = Test circuit impedance as measured from drain to ground.

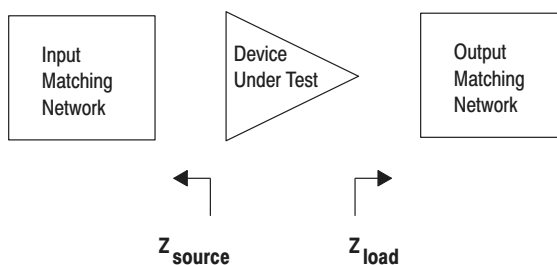
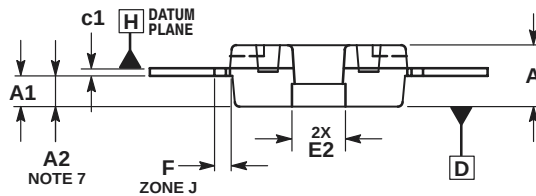
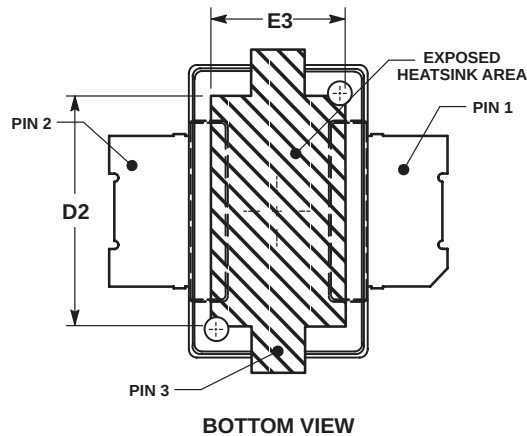
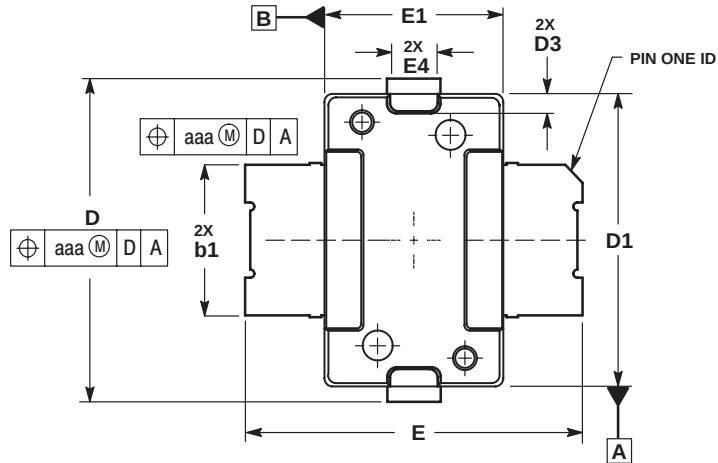


Figure 13. Series Equivalent Input and Output Impedance (MRF9045MBR1)

NOTES

PACKAGE DIMENSIONS



NOTES:

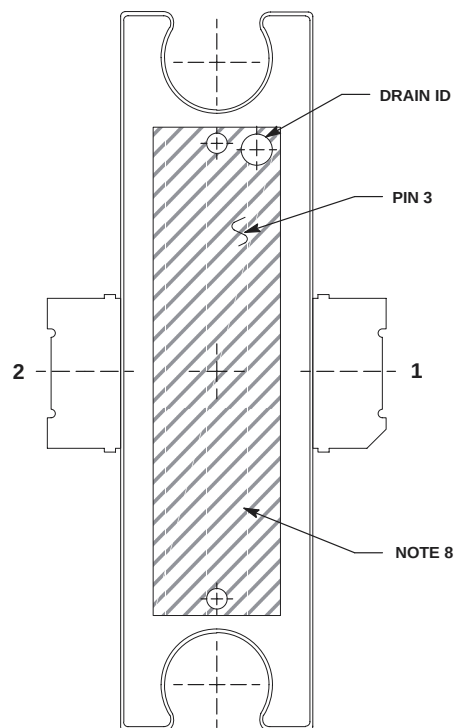
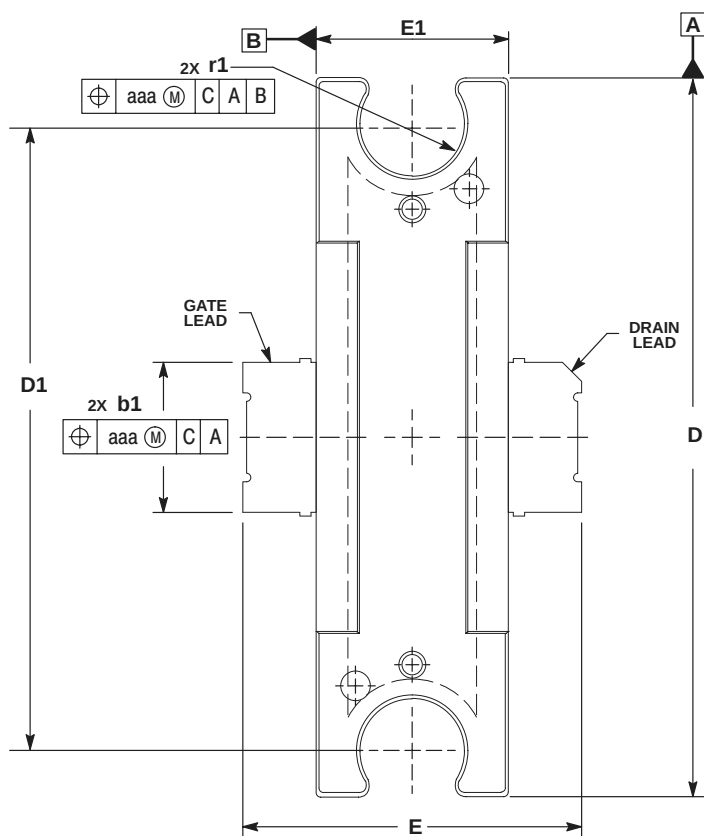
1. CONTROLLING DIMENSION: INCH.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
3. DATUM PLANE -H- IS LOCATED AT TOP OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE TOP OF THE PARTING LINE.
4. DIMENSIONS "D1" AND "E1" DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS .006 PER SIDE. DIMENSIONS "D1" AND "E1" DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -H-.
5. DIMENSION b1 DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE .005 TOTAL IN EXCESS OF THE b1 DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. DATUMS -A- AND -B- TO BE DETERMINED AT DATUM PLANE -H-.
7. DIMENSION A2 APPLIES WITHIN ZONE "J" ONLY.
8. DIMENSIONS "D" AND "E2" DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS .003 PER SIDE. DIMENSIONS "D" AND "E2" DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -D-.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.076	.084	1.93	2.13
A1	.038	.044	0.96	1.12
A2	.040	.042	1.02	1.07
D	.416	.424	10.57	10.77
D1	.376	.384	9.55	9.75
D2	.290	.320	7.37	8.13
D3	.016	.024	0.41	0.61
E	.436	.444	11.07	11.28
E1	.236	.244	5.99	6.20
E2	.066	.074	1.68	1.88
E3	.150	.180	3.81	4.57
E4	.058	.066	1.47	1.68
F	.025 BSC		0.64 BSC	
b1	.193	.199	4.90	5.06
c1	.007	.011	0.18	0.28
aaa	.004		0.10	

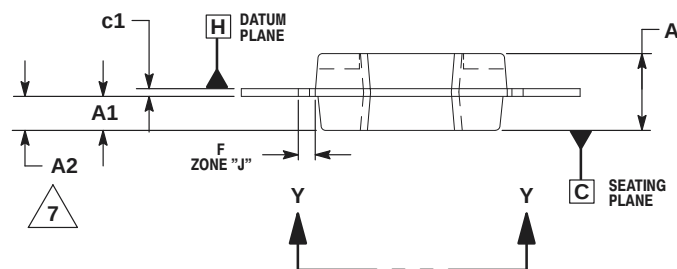
STYLE 1:

- PIN 1. DRAIN
2. GATE
3. SOURCE

CASE 1265-07
ISSUE F
TO-270
PLASTIC
MRF9045MR1



VIEW Y-Y



NOTES:

1. CONTROLLING DIMENSION: INCH.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
3. DATUM PLANE -H- IS LOCATED AT THE TOP OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE TOP OF THE PARTING LINE.
4. DIMENSIONS "D" AND "E1" DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS .006 PER SIDE. DIMENSIONS "D" AND "E1" DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -H-.
5. DIMENSION "b1" DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE .005 TOTAL IN EXCESS OF THE "b1" DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. DATUMS -A- AND -B- TO BE DETERMINED AT DATUM PLANE -H-.
7. DIMENSION A2 APPLIES WITHIN ZONE "J" ONLY.
8. CROSSHATCHING REPRESENTS THE EXPOSED AREA OF THE HEAT SLUG.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.098	.106	2.49	2.69
A1	.038	.044	0.96	1.12
A2	.040	.042	1.02	1.07
D	.926	.934	23.52	23.72
D1	.810 BSC		20.57 BSC	
E	.438	.442	11.12	11.23
E1	.246	.254	6.25	6.45
F	.025 BSC		0.64 BSC	
b1	.193	.199	4.90	5.05
c1	.007	.011	.18	.28
r1	.063	.068	1.60	1.73
aaa	.004		.10	

STYLE 1:
PIN 1. DRAIN
2. GATE
3. SOURCE

CASE 1337-02
ISSUE A
TO-272 DUAL LEAD
PLASTIC
MRF9045MBR1

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